



SSCU4N20TN4

N-Channel Enhancement Mode MOSFET

Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
20V	$\pm 12V$	4m Ω @4V5	65A
		5.5m Ω @2V5	

Description

The SSCU4N20TN4 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

100% UIS + ΔV_{DS} + R_g Tested!

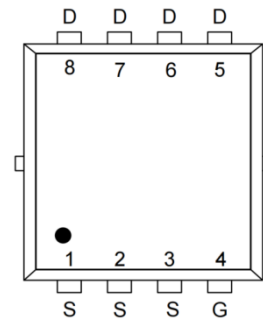
Applications

- PWM Applications
- Load Switch
- DC-DC Converters
- Wireless Chargers

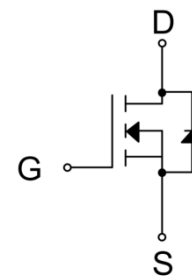
Ordering Information

Device	Package	Shipping
SSCU4N20TN4	PDFN3.3X3.3-8L	5000/Reel

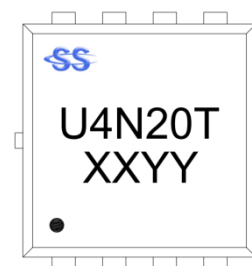
Pin configuration



PDFN3.3X3.3-8L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DS}	Drain-to-Source Voltage		20	V
V_{GS}	Gate-to-Source Voltage		± 12	V
I_D	Continuous Drain Current ^d	$T_C=25^{\circ}\text{C}$	65	A
		$T_C=100^{\circ}\text{C}$	35	
I_{DSM}	Continuous Drain Current ^a	$T_A=25^{\circ}\text{C}$	23	A
		$T_A=70^{\circ}\text{C}$	16	
I_{DM}	Pulsed Drain Current ^b		260	A
P_D	Power Dissipation ^c	$T_C=25^{\circ}\text{C}$	28	W
		$T_C=100^{\circ}\text{C}$	11.2	
P_{DSM}	Power Dissipation ^a	$T_A=25^{\circ}\text{C}$	3.3	W
		$T_A=70^{\circ}\text{C}$	2.1	
I_{AS}	Avalanche Current ^b $L=0.5\text{mH}$ Single Pulse		19	A
E_{AS}	Avalanche Energy ^b $L=0.5\text{mH}$ Single Pulse		90	mJ
T_J	Operation junction temperature		-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55~150	

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	38	$^{\circ}\text{C/W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	4.5	

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

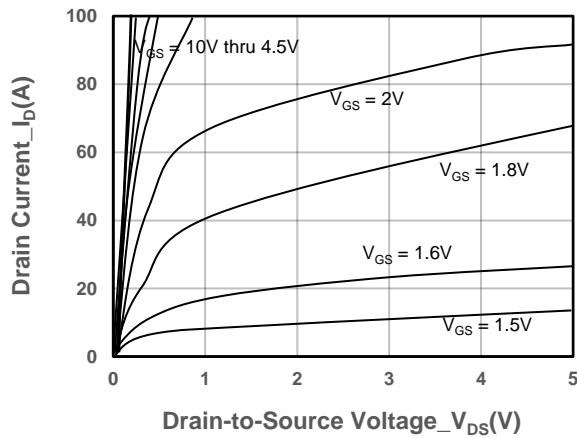


➤ **Electrical Characteristics (T_A=25°C unless otherwise noted)**

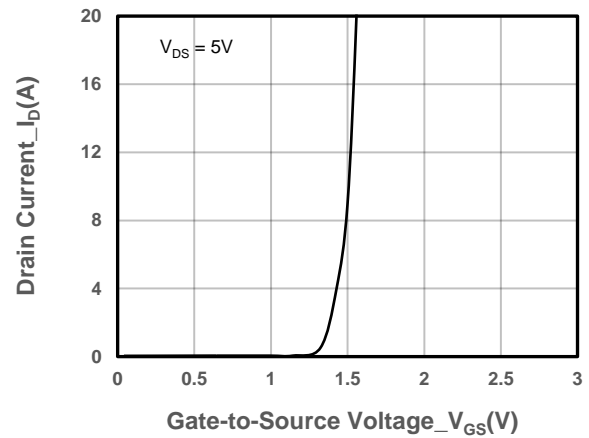
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250uA	20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.45	0.7	1.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 20A		4	6	mΩ
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 2.5V, I _D = 15A		5.5	8	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	uA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 10A			1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		1.2		Ω
Input Capacitance	C _{ISS}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz		3174		pF
Output Capacitance	C _{OSS}			398		
Reverse Transfer Capacitance	C _{RSS}			345		
Total Gate Charge	Q _G	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 15A		32		nC
Gate to Source Charge	Q _{GS}			7		
Gate to Drain Charge	Q _{GD}			10		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 15A, R _G = 3Ω		12		ns
Rise Time	T _r			34		
Turn-off Delay Time	T _{D(OFF)}			75		
Fall Time	T _f			91		
Diode Recovery Time	T _{rr}	I _F = 20A, di/dt = 100A/us		13.8		ns
Diode Recovery Charge	Q _{rr}	I _F = 20A, di/dt = 100A/us		4		nC



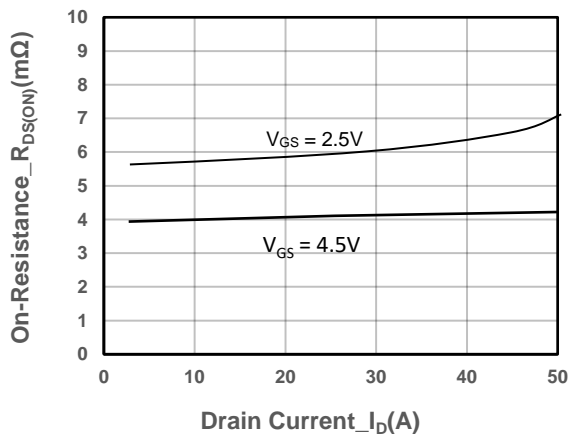
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



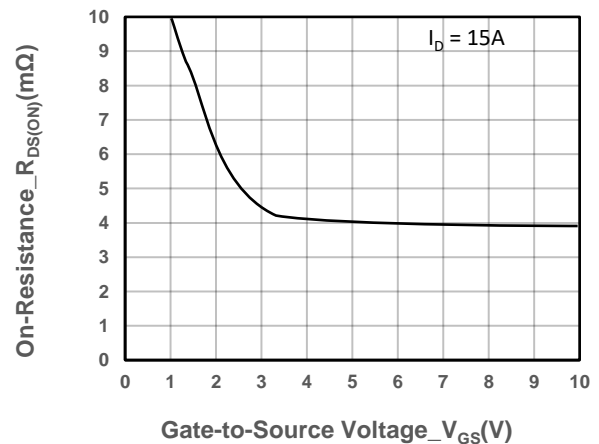
Output Characteristics



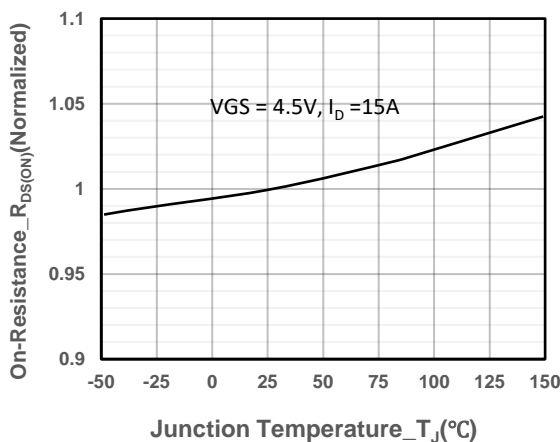
Transfer Characteristics



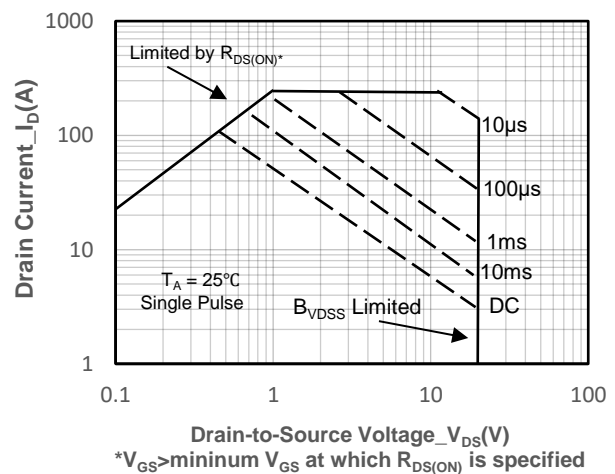
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

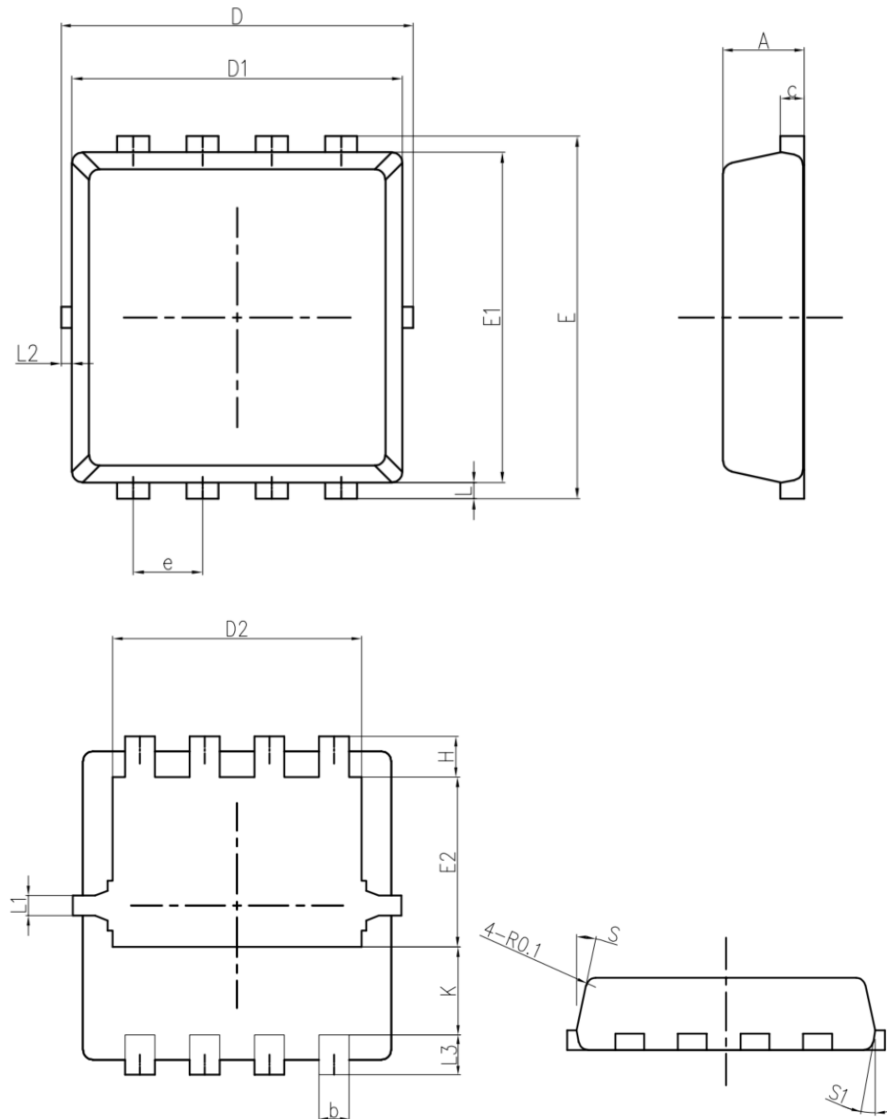


On-Resistance vs. Junction Temperature



Safe Operating Area vs. Junction-to-Ambient

➤ Package Information



COMMON DIMENSIONS (UNIT of MEASURE=MILLIMETER)											
SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	0.66	0.76	0.86	e	0.55	0.65	0.75	L	0.06	0.15	0.20
b	0.25	0.30	0.35	E	3.15	3.30	3.45	L1	0.10	0.20	0.30
c	0.19	0.20	0.22	E1	3.00	3.10	3.20	L2	0	0.10	0.15
D	3.15	3.30	3.45	E2	1.60	1.70	1.80	L3	0.30	0.40	0.50
D1	3.00	3.10	3.20	H	0.31	0.41	0.51	S	10°	12°	14°
D2	2.40	2.50	2.60	K	0.79	0.89	0.99	S1	8°	10°	12°



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